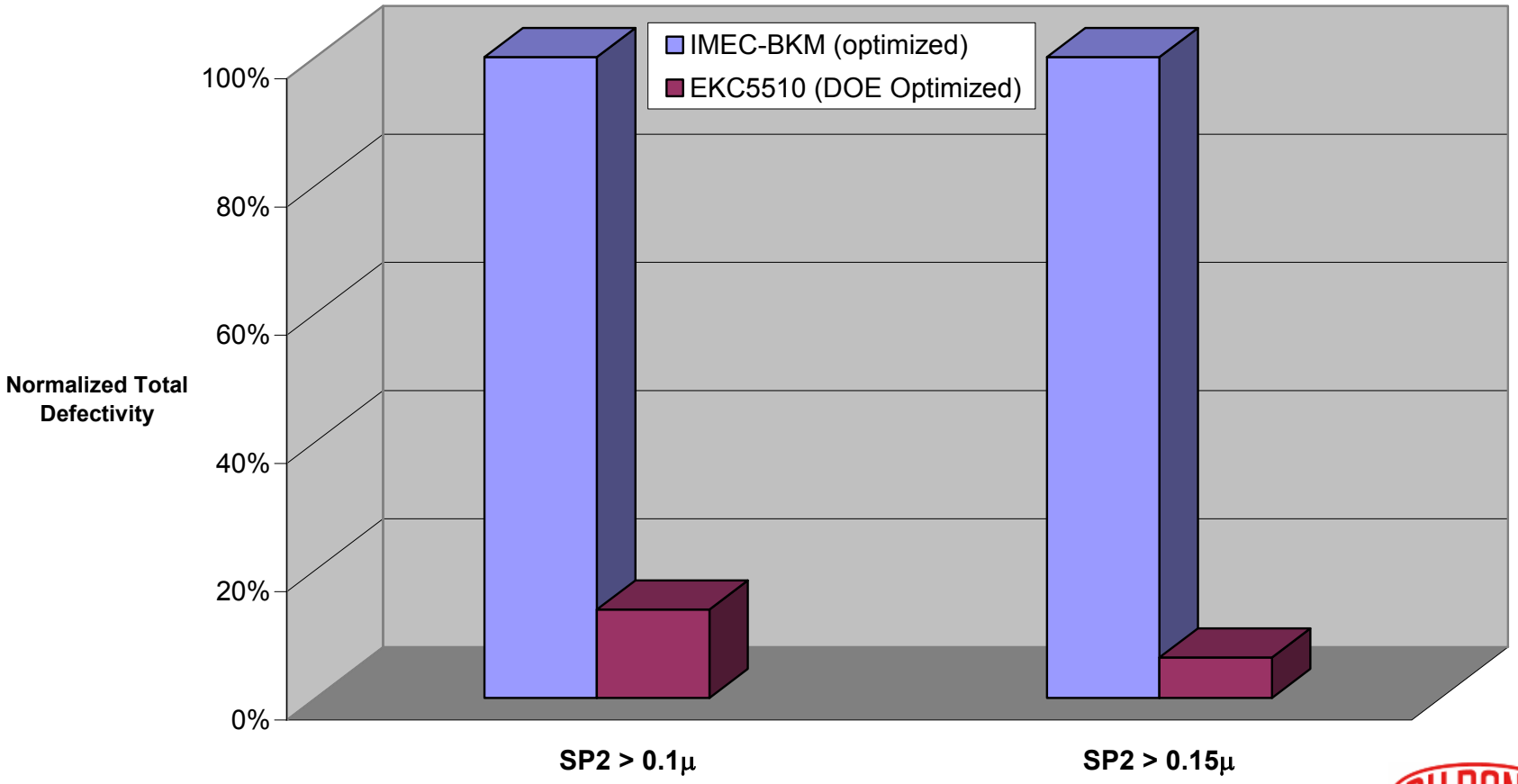
Why Use EKC PCMP5510™ ?

- **Industry proven in production at both Logic and Memory manufacturing sites:**
  - Leading Logic fab for > 6 years (currently at 65nm)
  - Leading Flash Memory fab for > 5 years
- **Provides very low cost of ownership through flexible dilution**
- **Capable of BTA removal from copper surfaces**
- **Reduces copper oxide ($Cu_{(x)}O$) thickness with high selectivity to Cu**
- **Effectively reduces surface particles/defects**
- **Significantly reduces surface trace metal contamination**
- **Eliminates copper dendrite formation**
- **Excellent compatibility on Cu, barrier, and low-k films**
- **Tunable to meet specific customer cleaning needs**
- **Compatible with advanced materials (advanced barrier and ULK films) allowing extendibility to advanced technology nodes**
- **High wafer throughput (not a limiting step in clustered tools)**
- **Environmentally sustainable solution**
  - Reduces DI water consumption; Waste stream compatible components

DUPONT®

Proven: Particle Removal
Slurry Removal Testing on Clustered Tool

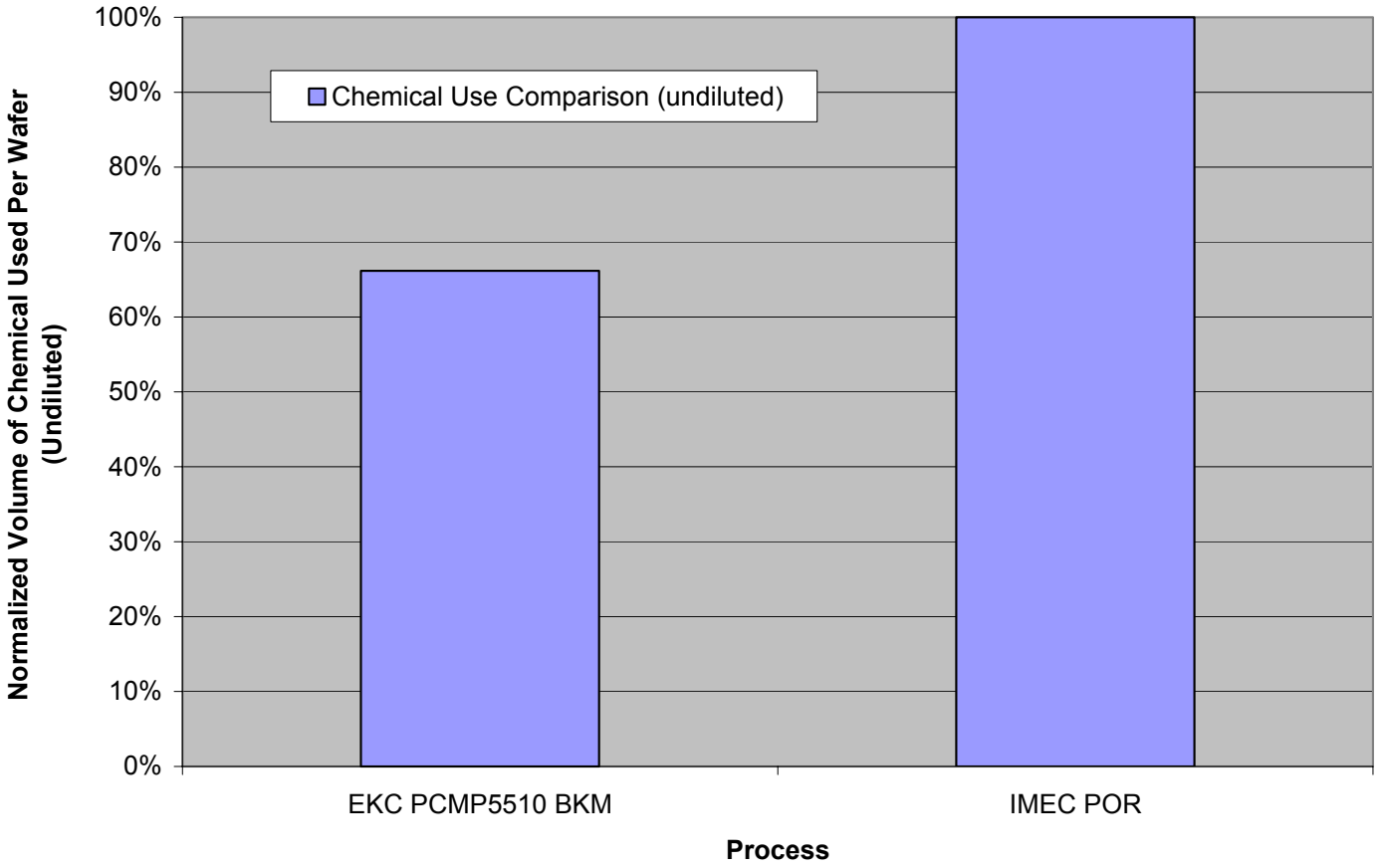
BDIIx 2.5 Cleaning Comparison using Clustered Tool (AMAT Reflexion2 LK) with TiN Metal Hardmask Integration Scheme (TiN / BDIIx 2.5). Barrier Slurry: pH ~ 10 Silica



Effective Particle Removal

Lower Cost of Ownership Achieved Through Higher Dilution

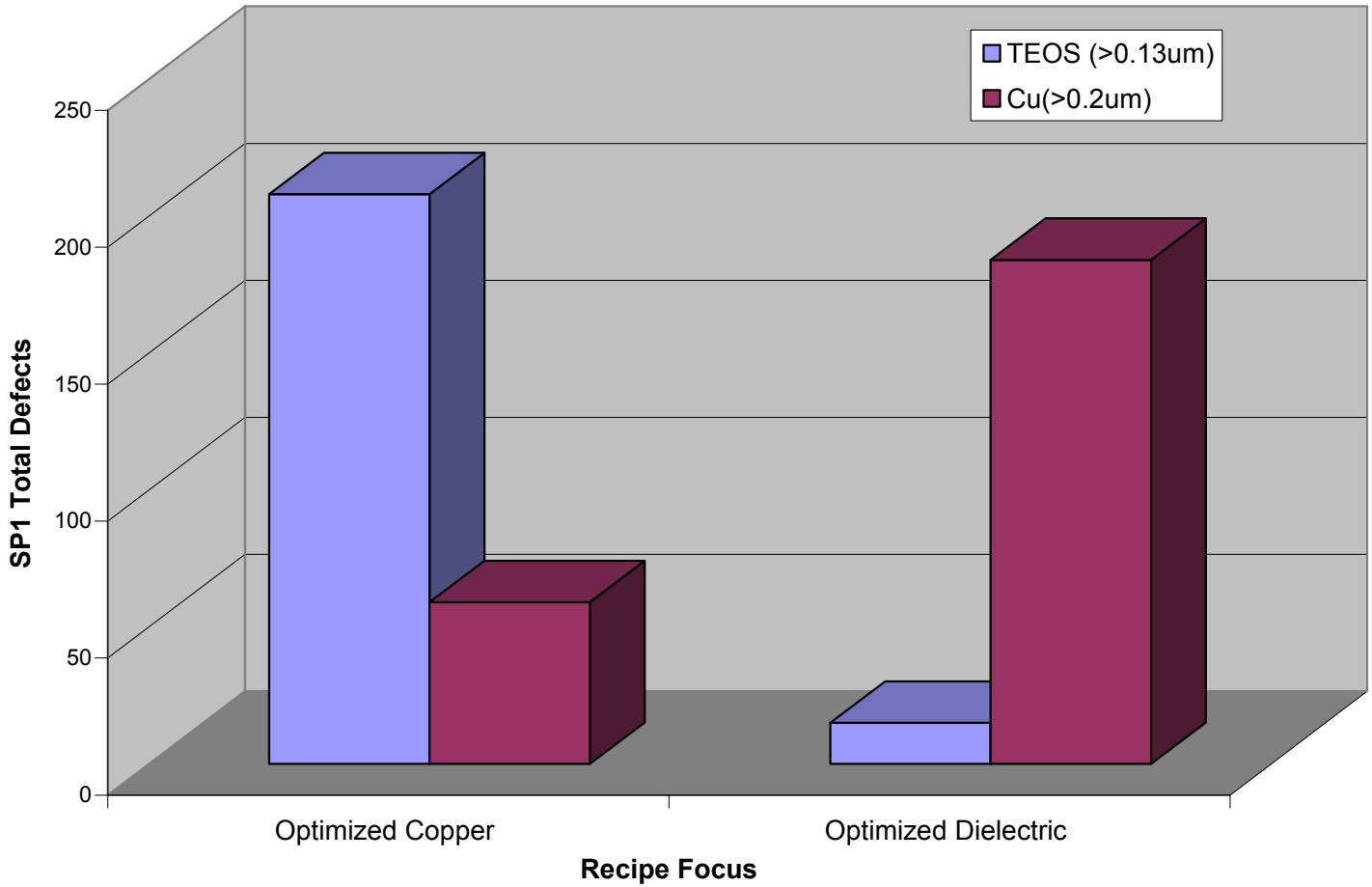
Comparison of Undiluted Chemical Volumes used Per Wafer for IMEC POR vs. EKC PCMP5510™ BKM on AMAT Reflexion2 LK Integrated CMP Platform



Cost Savings through Flexible Dilution

PCMP5510™ Allows Tunable Process to Meet Specific Customer Cleaning Requirements

Tunability of PCMP5510™ Resulting in Optimized Cleaning for Specific Films



Tunable Performance